

ONE SOURCE ONE SOLUTION



Die & Wafer Solutions



- Largest Global Die Distributor
- Next-Gen Materials: GaN, SiC
- Die Express Quick Turn Service
- Turnkey Wafer Processing: Wafer Thinning & Dicing, Pick & Place, Wafer Probe, Mapping & Inking, Visual Inspection
- Customized Output: Sawn on Foil, Waffle Pack, Gel-Pak, Tape & Reel
- Vendor Managed Inventory, Long Term Die & Wafer Storage
- EOL Die Sustainment Program
- Lot Acceptance Testing & Element Evaluation

Hi-Rel Products



- Memory, Logic, Analog, DC-DC Hybrids & PCBs, RF/Microwave, Diodes, Data Bus, SMD/5962, Couplers & Harnesses
- Packaging & Assembly: Precision Die Attach, Optoelectronic
- Hermetic: DIP, SOJ, LCC, FP, QFP, Gull Wing, PGA, Metal Can
- Plastic: CSP, BGA, QFN, ZIP
- QML Level Packaging
- Advanced Packaging: Flip-Chip/MCM, 2.5/3DHI, SiP, Chiplets, WLP, Novel Microfabrication
- Custom ASICs
- Turnkey Assembly, Test & Kitting

Testing & Qualification



- Electrical & Environmental Testing
- Device Characterization Testing
- FPGA, ASIC, RF, Memory, Analog, Logic, Mixed Signal & Discrete
- DMEA Trusted Source for Test and Process Screening
- PEMs/COTS Upscreening & Qual, Reliability Testing
- Advanced Chamberless Burn-In, HTOL/TOL
- ESD Characterization
- Acoustic Microscopy, X-Ray, XRF, PIND, Fine/Gross Leak Testing
- Counterfeit Mitigation Services

Component Modification



- Robotic Hot Solder Dip
- BGA Reballing
- CGA Attach
- Component Prep. & Lead Attach
- Trim & Form, and Reconditioning
- Component Harvesting
- Support Solutions: Tape & Reel, Marking, Labeling & Kitting, Bake & Package, IC Program, 3D Scan
- Supplier Managed Inventory (SMI)
- Serving All Standard Package Types
- NADCAP Certified

One Source Sustainment Solutions - Keeping Mission Critical Systems & Platforms Operational

Original Qualified Product

With access to the broadest supply of die, we will source originally qualified parts that have or will become EOL, avoiding costly requalification.

Form-Fit-Function Recreation

When original qualified die or components are not available, Micross has the expertise to reverse engineer devices and recreate equivalent devices.

Program Sustainment Management

Uninterrupted product supply through BOM monitoring, long term die & wafer storage and turnkey and supplier managed inventory



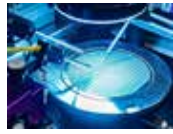
Facilities & Locations

16 World Class Manufacturing Operations (550,000+ ft²) in North America & Europe. AS9100 & ISO9001 Certified.

Die & Wafer Solutions



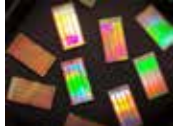
Apopka, FL
Die & Wafer Solutions
Wafer Processing & Test, Bare Die & Wafer Distribution



Los Alamitos, CA
SemiDice
Wafer Processing & Test, Bare Die & Wafer Distribution



Milpitas, CA
Silicon Turnkey Solutions
Electrical and Reliability Test, COTS/PEMs Upscreening & Qualification



Woburn, MA
Micross Express
Bare Die & Wafer Distribution, Passive Components, Same-Day Service, & Vendor Managed Inventory



Norwich, UK
Die & Wafer Solutions
Wafer Processing & Test, Bare Die & Wafer Distribution



Clearwater, FL
Counterfeit Mitigation
Counterfeit Detection Testing, Upscreening, and IC Programming

Hi-Rel Products



Apopka, FL
Hi-Rel Components
MCM / Hybrid Packaging, Assembly, Test and Hi-Rel Products



San Jose, CA
Hi-Rel Power Solutions
Hybrid DC-DC Converters and EMI Filters



Shirley, MA
Hi-Rel RF Solutions
GaN / GaAs RF & Microwave Switches, Amplifiers, & Attenuators



Sunrise, FL
Couplers & Harnesses
Hi-Rel MIL-STD-1553 Data Bus Couplers and Harness Assemblies



Raleigh, NC
Adv. Interconnect Technology
2.5/3D Heterogeneous Integration & Wafer Level Packaging (WLP)



Reynosa, MX
Hi-Rel Diodes
Hi-Rel Discrete Diodes and Assemblies (ISOPAC®)



Ballerup, DK
Hi-Rel Power Solutions
COTS and Custom Board-Based Power Products



Portsmouth, UK
Hi-Rel Components
MCM / Hybrid Packaging, Assembly, Test, and Hi-Rel Products

Component Modification Services



Manchester, NH
Component Modification
Robotic Hot Solder Dip (RHSD), Lead Attach, and Trim & Form



Round Rock, TX
Component Modification
BGA Reballing, Components Harvesting, and Solderability



Crewe, UK
Component Modification
Robotic Hot Solder Dip (RHSD), TCE, BGA Reballing, CGA, and Plating

Corporate Headquarters



Melville, NY
Micross Headquarters

Engineering & Program Management Support

Micross' highly experienced global field sales, and expert engineering teams provide complete application support from design specification to post production sustainment & program management.

Micross Heritage

With Over 45+ Years Experience, Micross has Strengthened it's Capabilities to Offer the Broadest Microelectronic Solutions Available from One Source.



Need Information?

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